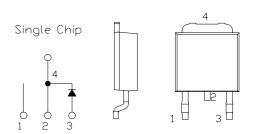
# Nihon Inter Electronics Corporation

 $\textbf{SBD} \quad \mathrm{Type} \,:\, EA30QS10\text{-}F$ 

#### **OUTLINE DRAWING**

#### **FEATURES**

- \* TO-252AA Case, Surface Mounting Device
- \* Low Forward Voltage drop
- \* Low Power Loss
- \* High Surge Capability
- \* 40 Volts thru 100 Volts Types Available
- \* Packaged in 16mm Tape and Reel



### Maximum Ratings

#### Approx Net Weight:0.30g

Rating		Symbol	EA30QS10-F			
Repetitive Peak Reverse Voltage		V <sub>RRM</sub>	100			
Average Rectified Output Current	P.C.Board mounted *	Io	1.6	Ta=34°C	50Hz Half Sine Wave	A
	-		3.0	Tc=133°C	Resistive Load	
RMS Forward Current		I <sub>F(RMS)</sub>	4.71			Α
Surge Forward Current		Ifsm		50Hz Half Non-repetit	A	
Operating JunctionTemperature Range		Tjw	- 40 to + 150			°C
Storage Temperature Range		Tstg	- 40 to + 150			°C

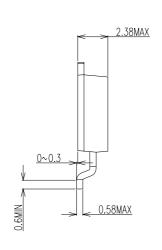
#### **Electrical** • Thermal Characteristics

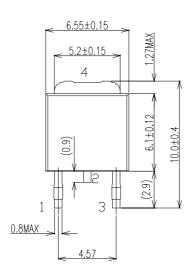
Characteristics		Symbol	Conditions	Min	Тур	Max	Unit
Peak Reverse Current		$I_{RM}$	Tj=25°C,V <sub>RM</sub> =V <sub>RRM</sub>	-	-	1.0	mA
Peak Forward Voltage		$V_{\rm FM}$	$Tj=25^{\circ}C,I_{FM}=3$ A	-	-	0.85	V
Thermal	Junction to Ambient	Rth(j-a)	P.C.Board mounted *	-	-	80	°C/W
Resistance	Junction to Case	Rth(j-c)	-	-	-	6	°C/W

<sup>\*</sup> Print Land = 20x20 mm

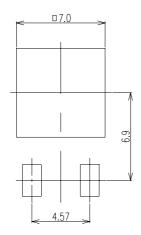
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### EA30QS10-F OUTLINE DRAWING (Dimensions in mm)





SOLDERING PAD



Single Chip

